

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

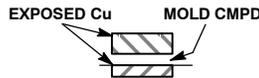
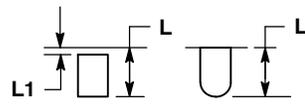
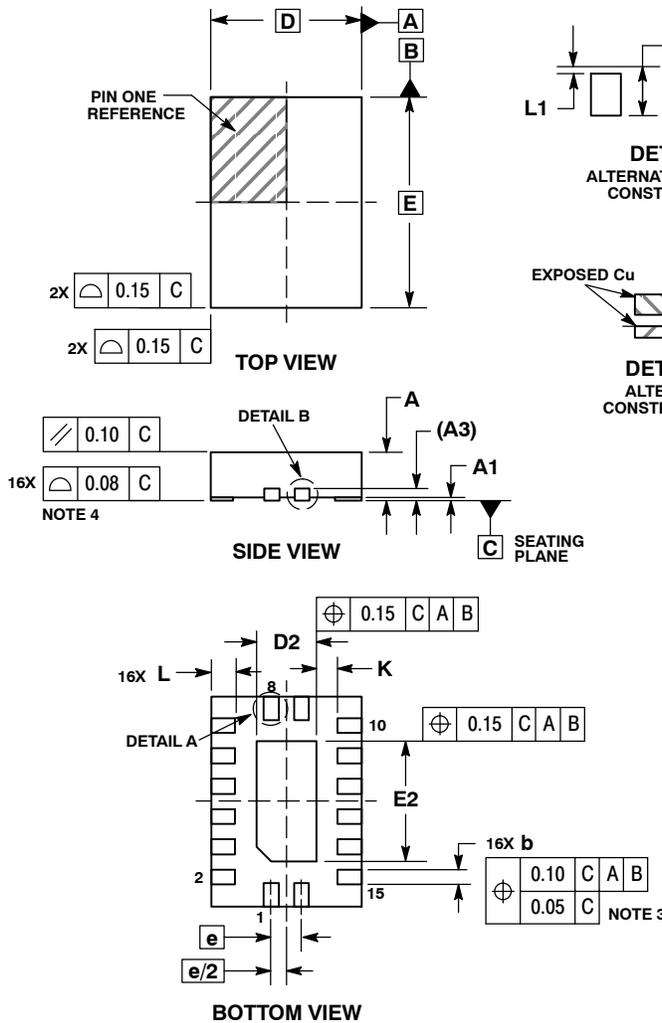
ON Semiconductor®



SCALE 2:1

QFN16, 2.5x3.5, 0.5P
CASE 485AW-01
ISSUE O

DATE 11 DEC 2008



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| DIM | MILLIMETERS | |
|-----|-------------|------|
| | MIN | MAX |
| A | 0.80 | 1.00 |
| A1 | 0.00 | 0.05 |
| A3 | 0.20 REF | |
| b | 0.20 | 0.30 |
| D | 2.50 BSC | |
| D2 | 0.85 | 1.15 |
| E | 3.50 BSC | |
| E2 | 1.85 | 2.15 |
| e | 0.50 BSC | |
| K | 0.20 | --- |
| L | 0.35 | 0.45 |
| L1 | --- | 0.15 |

GENERIC MARKING DIAGRAM*

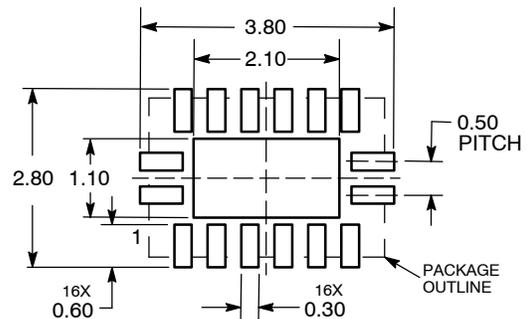


- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| STATUS: | ON SEMICONDUCTOR STANDARD | |
| NEW STANDARD: | | |
| DESCRIPTION: | QFN16, 2.5X3.5 | PAGE 1 OF 2 |

